



UNITED STATES PATENT AND TRADEMARK OFFICE

Supp.
Pre Amet B
Runeep
10/13/02

TECHNICAL
UNIT

In re the Application of: Norio FUKASAWA et al.

Serial No.: 09/766,656

Group Art Unit: 2814

Filed: January 23, 2001

Examiner: To be assigned

For: **METHOD AND MOLD FOR MANUFACTURING SEMICONDUCTOR DEVICE,
SEMICONDUCTOR DEVICE, AND METHOD FOR MOUNTING THE DEVICE**

SUPPLEMENTAL PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

February 21, 2002

Sir:

Prior to examination of this application, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 87-97 without prejudice or disclaimer and add new claims 98-110 as

follows:

98. (New) A method for fabricating a semiconductor device comprising:

a resin sealing step of loading a substrate on which semiconductor elements having protruding electrodes are formed to a mold, and supplying a sealing resin to positions of the protruding electrodes so as to form a first resin layer which seals the protruding electrodes and the substrate;

a protruding electrode exposing step of exposing at least ends of the protruding electrodes from the first resin layer; and

a separating step of cutting the substrate together with the first resin layer so that the semiconductor elements are separated from each other.